

Features

- Ideal for automated placement
- Low forward voltage drop
- Low leakage current
- Moisture sensitivity: level 1, per J-STD-020
- AEC-Q101 qualified
- Low profile



Package: eSGB (SMAF)

Applications

For use in general purpose rectifications in lighting, cellular phones, portable devices, power supplies and other consumer applications.



Maximum Ratings (T_A = 25°C unless otherwise noted)

Parameter	Symbol	LH5	LH6	LH7	Unit
Maximum Repetitive Peak Reverse Voltage	V _{RRM}	600	800	1000	V
Maximum RMS Voltage	V _{RMS}	420	560	700	V
Maximum DC Blocking Voltage	V _{DC}	600	800	1000	V
Maximum Average Forward Rectified Current	I _{F(AV)}	1.0			A
Peak Forward Surge Current (8.3 ms single half sine-wave superimposed on rated load)	I _{FSM}	30			A
Operating Junction and Storage Temperature Range	T _J , T _{STG}	- 55 to + 150			°C

Electrical Characteristics (T_A = 25°C unless otherwise noted)

Parameter	Test Conditions	Symbol	LH5	LH6	LH7	Unit
Maximum Instantaneous Forward Voltage	1 A	V _F	1.7			V
Maximum DC Reverse Current at rated DC Blocking Voltage	T _A =25°C	I _R	5			μA
	T _A =125°C		50			
Maximum Reverse Recovery Time	I _F =0.5A, I _R =1.0A, I _{rr} =0.25A	t _{rr}	75			ns
Typical Junction Capacitance	4.0 V, 1 MHz	C _J	15			pF

Ratings and Characteristics Curves ($T_A = 25^\circ\text{C}$ unless otherwise noted)

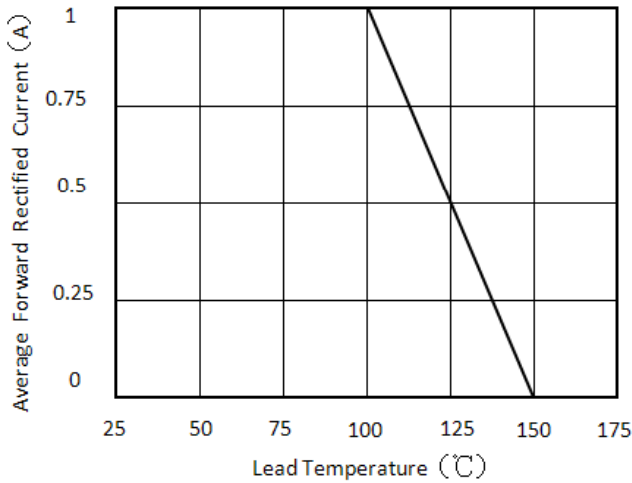


Figure 1. Forward Current Derating Curve

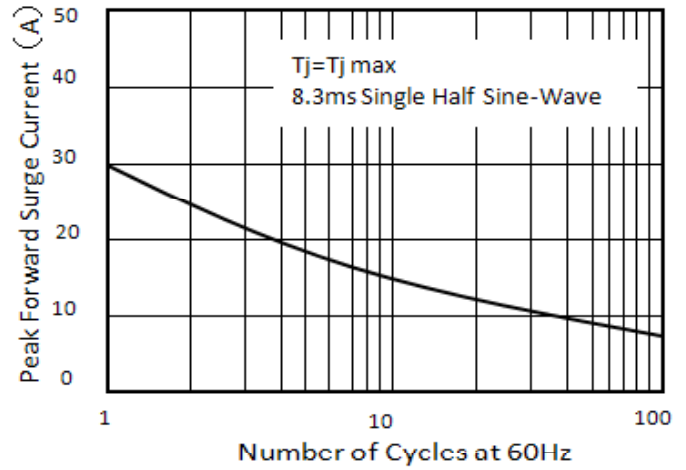


Figure 2. Maximum Non-Repetitive Peak Forward Surge Current

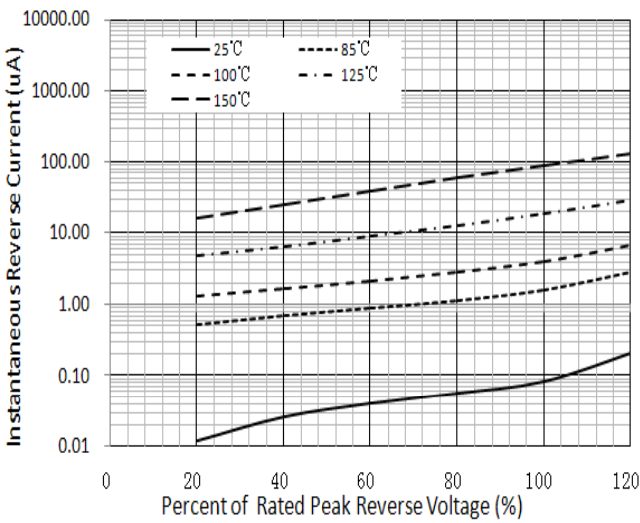


Figure 3. Typical Reverse Characteristics

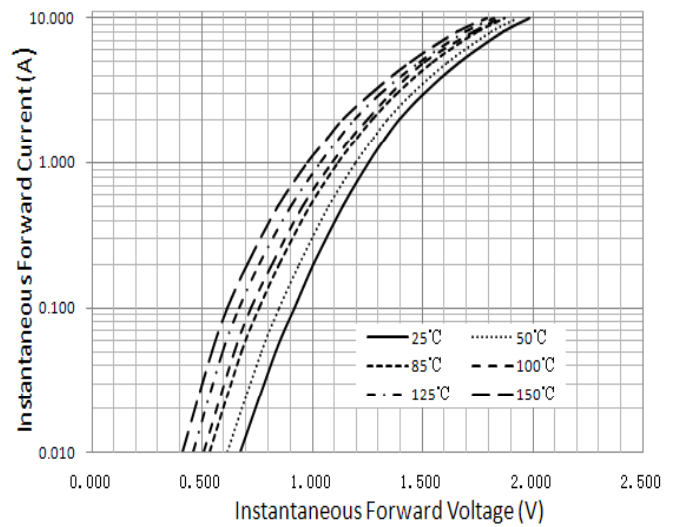
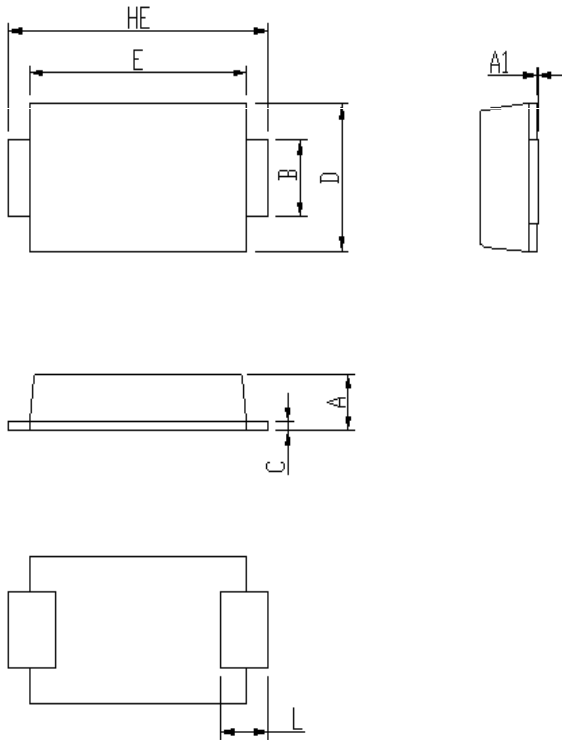


Figure 4. Typical Instantaneous Forward Characteristics

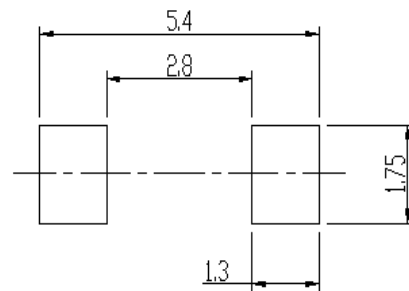
Package Outline Dimensions

eSGB (SMAF)



DIM	Unit: mm		Unit: inch	
	MIN	MAX	MIN	MAX
A	0.92	1.08	0.036	0.043
A1	0	0.1	0.000	0.004
B	1.25	1.45	0.049	0.057
C	0.1	0.25	0.004	0.010
D	2.6	2.8	0.102	0.110
E	4.1	4.3	0.161	0.169
L	0.7	1.1	0.028	0.043
HE	4.8	5.2	0.189	0.205

Soldering footprint



Packing Information

3000 pcs/Reel , 12mm Tape, 13" Reel

Tape & Reel Specification

